U7 is not included or supported in this design.
It will be included in a future TI Design.
Assembly Note
ZZ1
These assemblies are ESD sensitive, ESD precautions shall be observed.

Assembly Note
ZZ2
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Assembly Note
ZZ3
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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